

RoHS

Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE $\pm 0.05$ )

SPECIFICATIONS

Rated Current:3.0AMP

Contact Resistance:20m $\Omega$  Max

Withstand Voltage:500V AC/DC

Insulation Resistance:1000M $\Omega$  Min

Operation Temperature:-40 $^{\circ}$ c to +105 $^{\circ}$ c

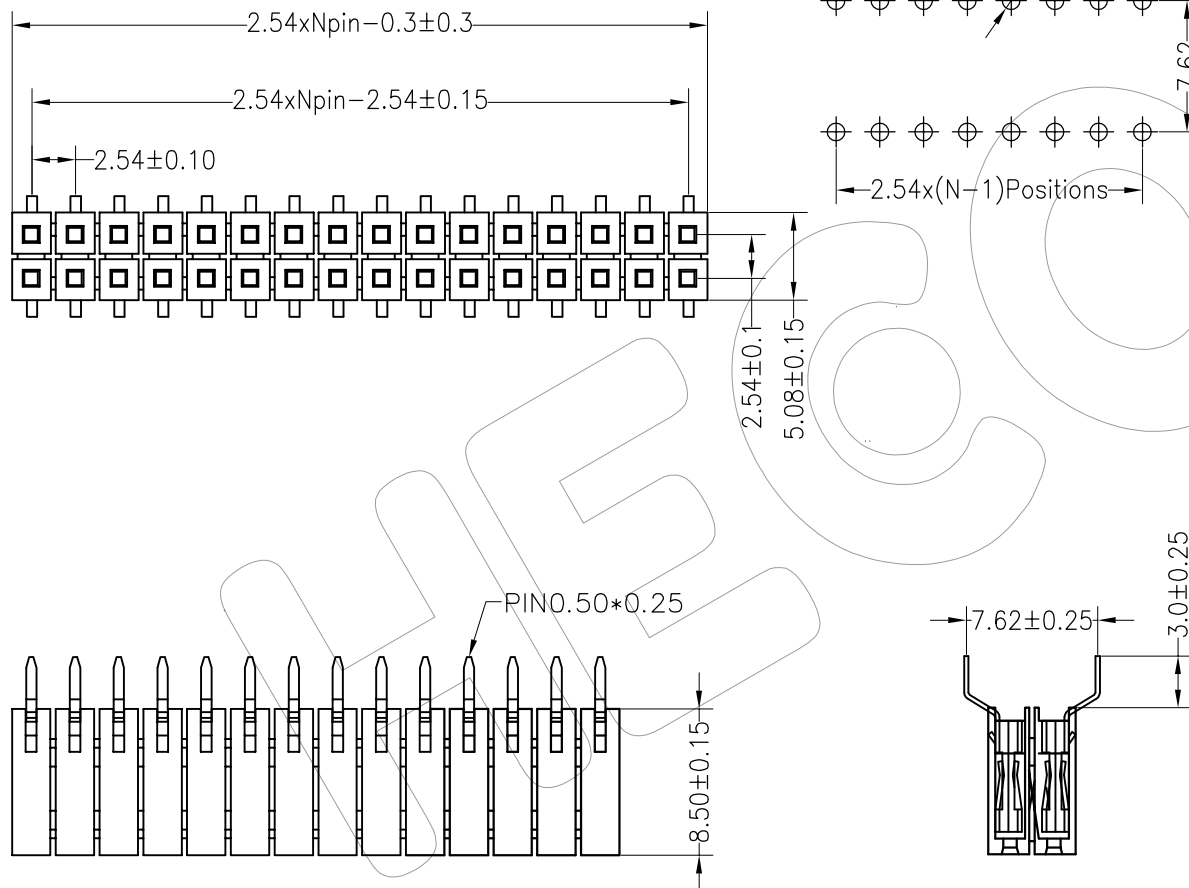
Contact Material:Brass

Contact Plating:Au or Sn Over Ni

Insulator Material:Polyester(UL94V-0)

Standard: PA6T

Max.Processing Temp: 230 $^{\circ}$ C for 30-60 seconds  
(260 $^{\circ}$ C for 10 seconds)



Ordering Information

HC-FH485-2 XX X N XX W T X 01

| No. of Pins | Insulator Material Option                                   | Post                      | Contact Plating                                                                                                            | Packing                                                      | Special |
|-------------|-------------------------------------------------------------|---------------------------|----------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------|---------|
| 2*2~2*40P   | A=BK-PBT<br>C=BK-PA6T<br>D=BK-PA46<br>E=BK-PA9T<br>F=BK-LCP | W=With Post<br>N=W/O Post | G0:Gold Flash<br>G1:3U" Gold<br>G2:5U" Gold<br>G3:10U" Gold<br>G4:15U" Gold<br>G5:30U" Gold<br>S0:Gold Flash/Tin<br>SN:Tin | A=Tray<br>T=Tube<br>P=Tube+Cap<br>R=Reel+Cap<br>M=Reel+Mylar |         |

OPERATION

X.X  $\pm 0.30$

X.XX  $\pm 0.20$

X.XXX  $\pm 0.10$

Angle  $\pm 3^{\circ}$

DIM TOL

DRAW

Lu jin ying

CHECK

APPROVE

SCALE

FIT

UNIT

mm

SIZE

A4

SHEET

1/1

PROJ.

$\phi$   $\nabla$

HECON

东莞市禾康电子有限公司  
DONGGUAN HECON ELECTRONICS CO.,LTD

PART NO.

HC-FH485-2XXXNXXWTX01

TITLE:

A0

2023.04.27

NEW DRAWING

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

DIM

TOL

APPROVE

PROJ.

$\phi$   $\nabla$

PART NO.

HC-FH485-2XXXNXXWTX01

TITLE: